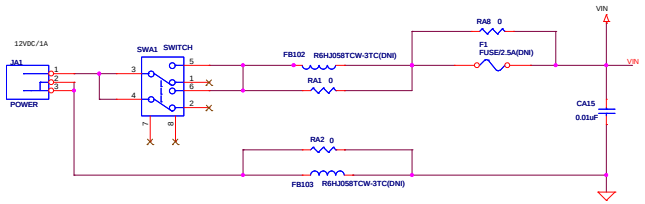
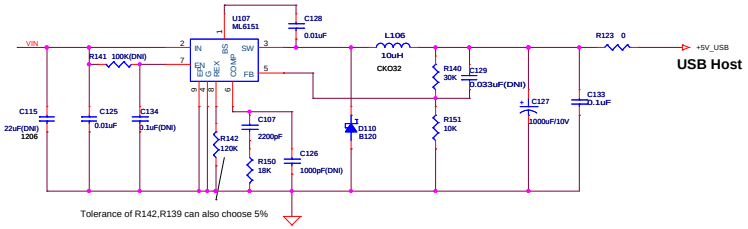
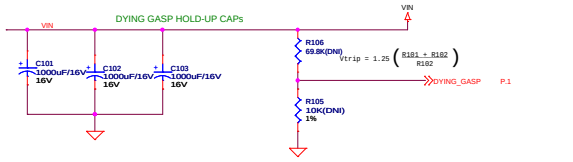
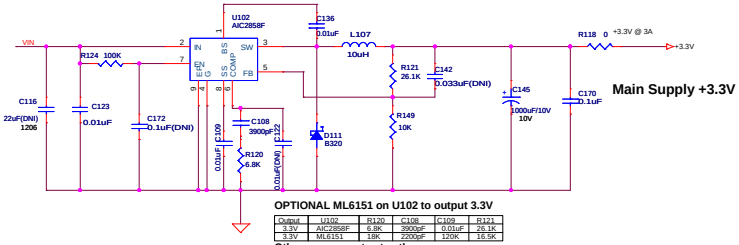
+12VDC Regulated Input

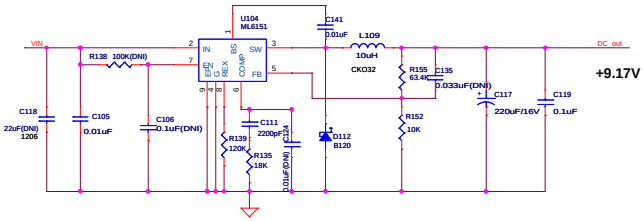


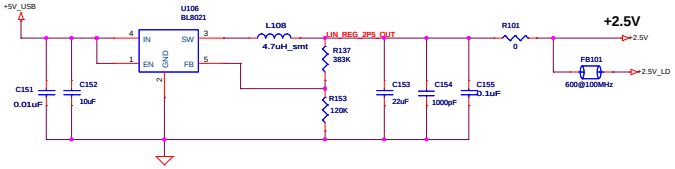


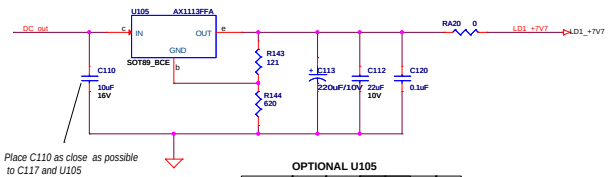


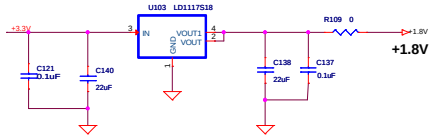


Output	U102	R120	C108	C109	R121
3.3V	AIC2858F	6.8K	3900pF	0.01uF	26.1K
3.3V	ML6151	18K	2200pF	120K	16.5K



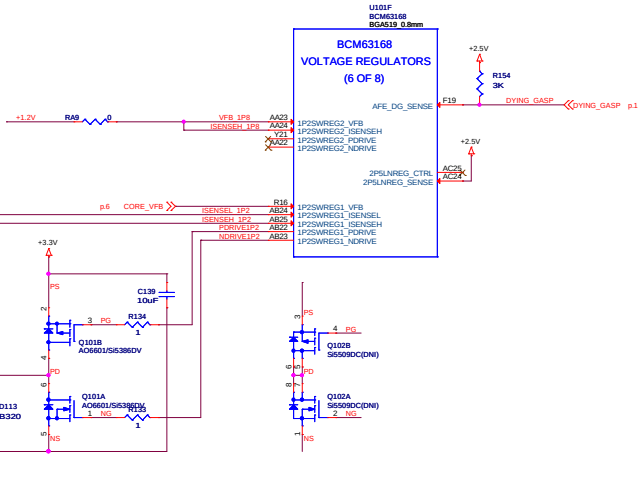




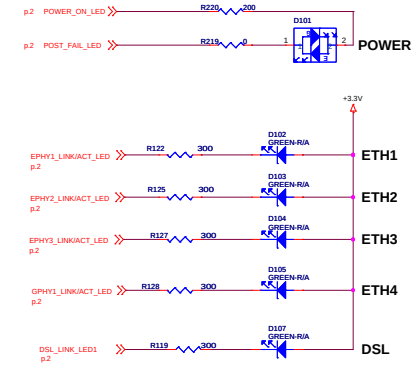


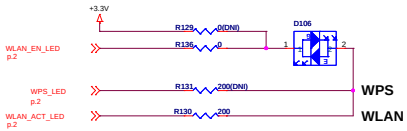
OPTIONAL U105

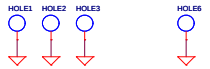
	U104	U105	R155	R152	R143	R144
U104	7.7V	DNI	52.3K	10K	DNI	DNI
U104+U105	9V	7.7V	62K	10K	121	620



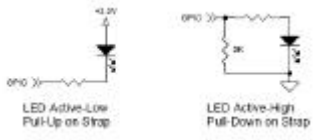
FRONT PANEL LEDs







If a pull-down resistor is added to a strap pin which drives an LED, the LED driver will automatically invert from active low to active high. In this case, connect the LED to be driven as active high. Note this inversion is true even when the LED is driven from the shift register.



DDR SDRAM layout rules:

All timing is relative the CLK/CLKb that arrive at the destination DDR SDRAM chip.

1) X = CLK/CLKb should be a matched differential pair with a length < 4"
2) Address and control should be X +/- 20mm
3) DQS and DQM should be X +/- 20mm
4) All DQs should match corresponding byte lane DQS/DQMs within +/- 10mm
5) Trace impedances should be 50 ohms +/- 10% (45-55 ohms)
6) Route VREF with 30-mil trace and at least 1 high quality ceramic bypass capacitor for each connection to a device.
7) All traces should have a >= 3 to 1 spacing ratio from the reference GND/PWR layer. (e.g. 15 mil line-to-line spacing for a 5 mil dielectric thickness)

Place C201-C218, close to U201

C201 C202 C203 C204 C205 C206 C207 C208 0.1uF
C209 C210 C211 C212 C213 C214 C215 C216 0.1uF
C217 10uF

U201 DDR2(32X16) BGA84 0.8mm

16b DDR2 SDRAM 32Mx16

NC = A2,E2

MAIN MEMORY DDR2 SDRAM 32-256 MBYTES

Place R203 as close as possible to U201

R203 100

U101A BCM63168 BGA519 0.8mm

BCM63168 MEMORY AND GPIO (1 OF 8)

R201 220
Y201 20.000MHz
C219 22pF
C220 33pF
XTAL_OUT XTAL_IN

SPI_CLK SPI_MISO SPI_MOSI SPI_SSB0 SPI_SSB1
R204 33

U211 S25FL032A
U210 SOB-200 FLASH(DNI)
C221 0.1uF
POR_RESET_B

LED USAGE:

a) LED connections only supported on LED[23:0]
b) USB_DEVICE_LED always use ball B3
c) INET_LED always use LED[8]
d) EPHY[3:1]_ACT_LED always use LED[11:9]
e) GPHY_ACT_LED always use LED[12]
f) EPHY[3:1]_SPD_LED always use LED[15:13]
g) GPHY_SPD_LED[1:0] always use LED[1:0]
h) WLAN LED only supported through GPIO[38:36]
i) Applications using NAND flash cannot access LED[7:2] through GPIO[7:2], and may shift out LED[7:0] through SERIAL_LED_CLK and SERIAL_LED_DATA.

! Bootstrap inputs are muxed onto GPIO[31:24,21,19,17:15,13,11,7:5,3,1:0]. Be aware that placing a pull-down resistor on any of these gpio will change the default bootstrap configuration.

OPTIONAL NAND FLASH(R238) MEMORY: 64-1000 MBYTES

C226 0.1uF(DNI) C227 0.1uF(DNI)
U208 64Mx8 3.3V NAND(DNI) TSOP48

R225 1K 1%
R210 1K 1%
C229 0.1uF C231 0.1uF C232 0.1uF
DDR_VREF
Place C229 near R210, R225.
Place one at each IC pin.

RN201 10K(DNI)
R212 240 1%
R213 10K

R214 10K
R205 3K
R206 1K (DNI)
R215 3K
R216 0(DNI)
R217 0
R218 0
SW203 PB-SPST-MOM-R/A
MANUAL RESET
SYS_RESET_B
RESET_OUT
RESTORE_CNFG
POR_RESET_B

C224 22pF C225 22pF

GPIO[51:40] are not accessible on a 4-layer PCB. I/O voltage of GPIO[51:40] is provided by MII2_VDDO. Connect to 3.3V if any of GPIO[51:40] are used. GPIO[51:36] do not have internal pull ups.

Shift registers for serial LED driver are shown as an example.

U206 74HC164D SO14
U207 74HC164D SO14
C222 0.1uF C223 0.1uF
SERIAL_LED_DATA SERIAL_LED_CLK

BCM63168 Strap Options

Strap settings change for B0 and C0 or later silicon

NAND_SPARE_16B

Silicon Revision	B0	C0
16 Bytes	0	1
27 Bytes	1	0

NAND_ENABLE_ECC

Silicon Revision	B0	C0
Enable	0	1
Disable	1	0

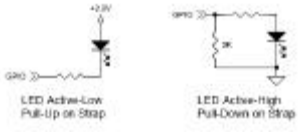
NAND ECC SEL[2:0]

Silicon Revision	B0	C0
1-bit Hamming	001	111
4-bit BCH	010	100
8-bit BCH	011	101
12-bit BCH	100	010

* All other values = No ECC

SERIAL_LED_CLK	GPIO_0	DDR_SPEED_GRADE_FAST	R247	4.7K(DNI)
SERIAL_LED_DATA	GPIO_1	RESERVED	R248	4.7K(DNI)
NAND_RB0	GPIO_3	NAND_SPARE_16B	R252	4.7K(DNI)
NAND_D0	GPIO_5	NAND_ECC_SEL[0]	R249	4.7K(DNI)
NAND_D1	GPIO_6	NAND_ECC_SEL[1]	R250	4.7K(DNI)
NAND_D2	GPIO_7	NAND_ECC_SEL[2]	R251	4.7K(DNI)
GPIO11	GPIO_11	RESERVED	R267	4.7K(DNI)
SELECT_DDR2/DDR3n	GPIO_13	SELECT_DDR2/DDR3n	R254	4.7K(DNI)
GPIO15	GPIO_15	SPI_SLAVE_DISABLE	R231	4.7K(DNI)
GPIO16	GPIO_16	SPI_CLK_50MHZ/20MHZn	R232	4.7K(DNI)
GPIO17	GPIO_17	SPI_FLASH_ADDR24	R233	4.7K(DNI)
GPIO19	GPIO_19	NAND_ENABLE_ECC	R235	4.7K(DNI)
POST_FAIL_LED	GPIO_21	BOOT_SPI/NANDn	R238	4.7K(DNI)
NAND_D3	GPIO_24	RESERVED	R239	4.7K(DNI)
NAND_D4	GPIO_25	RESETOUT_DLY[0]	R240	4.7K(DNI)
NAND_D5	GPIO_26	RESETOUT_DLY[1]	R241	4.7K(DNI)
NAND_D6	GPIO_27	RESETOUT_DLY[2]	R242	4.7K(DNI)
NAND_D7	GPIO_28	MIPS/DDR_CLK_SEL[0]	R243	4.7K(DNI)
NAND_ALE	GPIO_29	MIPS/DDR_CLK_SEL[1]	R244	4.7K(DNI)
NAND_WEB	GPIO_30	MIPS/DDR_CLK_SEL[2]	R245	4.7K(DNI)
NAND_CLE	GPIO_31	MIPS/DDR_CLK_SEL[3]	R246	4.7K(DNI)

If a pull-down resistor is added to a strap pin which drives an LED, the LED driver will automatically invert from active low to active high. In this case, connect the LED to be driven as active high. Note this inversion is true even when the LED is driven from the shift register.



Ephy 10/100 and GPHY - Layout Guidelines & Notes

1. *Route RDN, RDP and TDN, TDP pairs differentially, with 100ohm differential impedance, adjacent to the ground plane.*
2. *Keep differential pairs within a port separated by 3H distance and pairs between ports separted by 5H where H is the hieght of traces above the ground plane, i.e. H = the dielectric thickness.*
3. *Match differential pair trace length within the pair (P and N) to 10mils. No need to match trace length between differential pairs (RD and TD).*

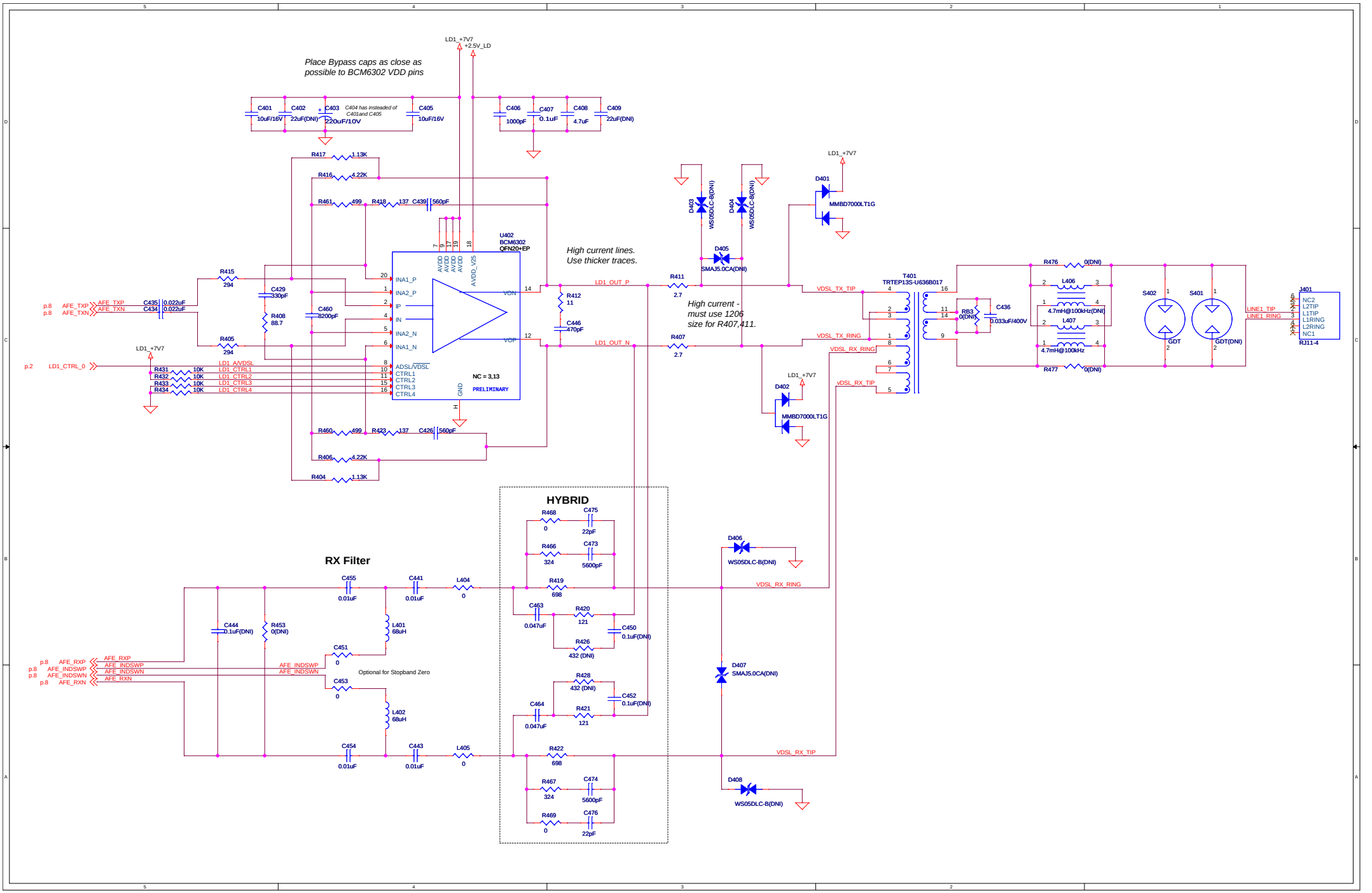
Route PCIe traces with 100ohm differential characteristic impedance.

USB2.0 - Layout Guidelines & Notes

1. *The Dp and Dn traces are length matched, with max differential skew, within 20mils*
2. *Differential trace length must be less than 5 inches*
3. *No more than 2 vias per trace, prefer zero.*
4. *Never split the ground plane under differential pair routing*
5. *Route differential pairs above the GND plane.*
6. *Differential impedance is 90 ohms for USB.*
7. *Adjacent differential pairs should be separated by at least 3 times the trace width. (e.g. 7.5 mil trace, leave >22.5mils between adjacent diff pairs)*
8. *Stitch gnd vias around each differential pair, but NOT between a given pair.*

The package of R316/R317 is RC0402, but choose RC0603 in the BOM

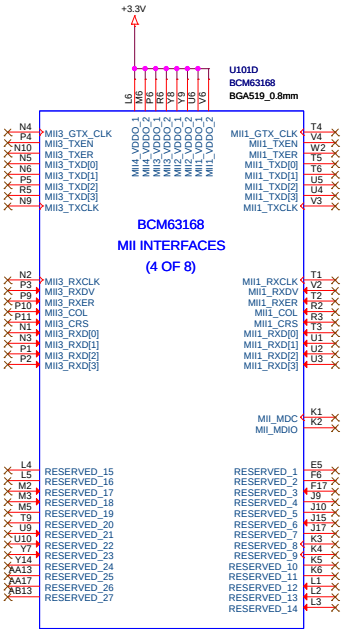
SERIAL CONSOLE PORT

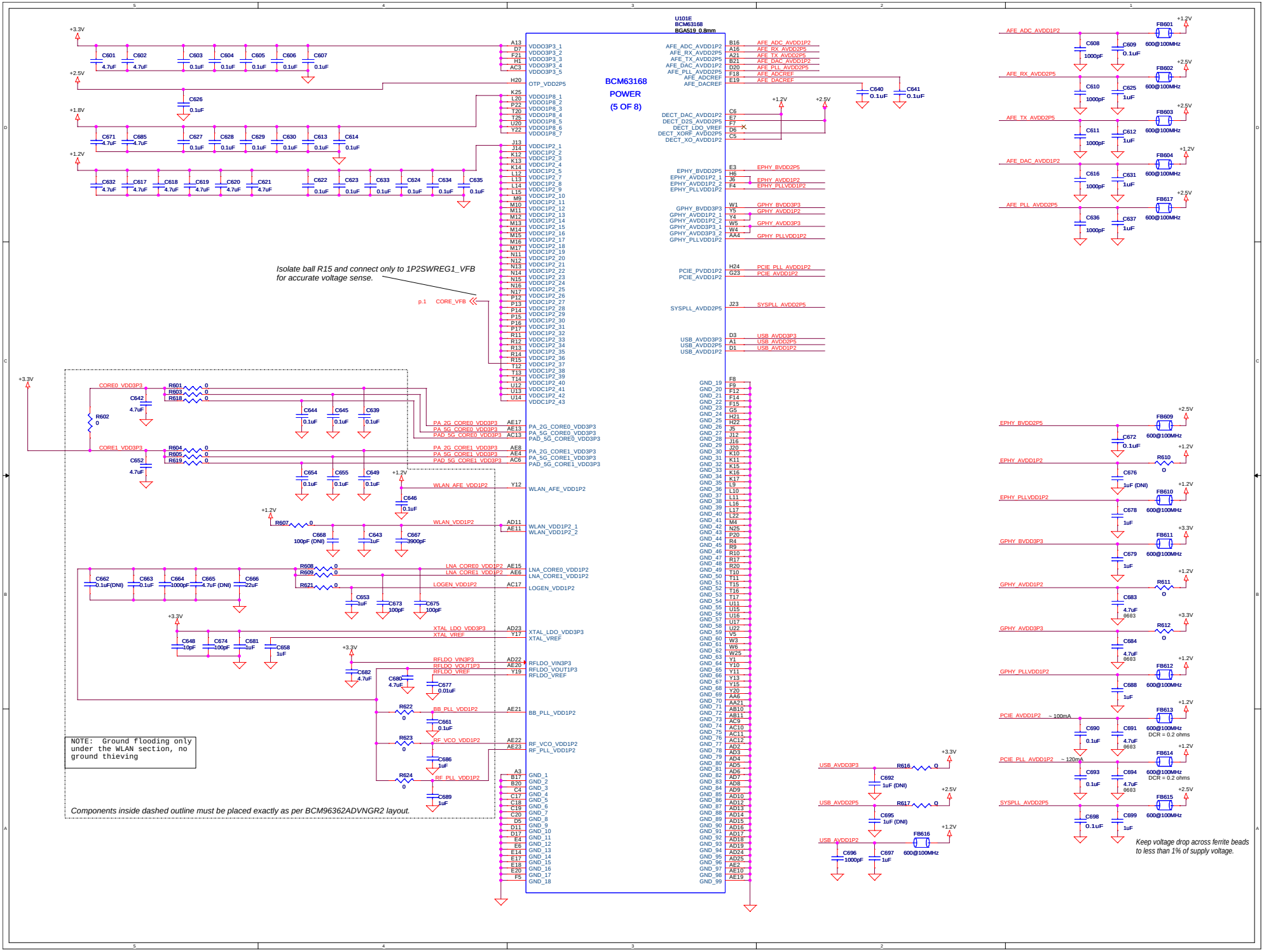

Place Bypass caps as close as possible to BCM6302 VDD pins
LD1_+7V7
+2.5V_LD
C401 10uF/16V
C402 22uF(DNI)
C403 220uF/10V
C404 has insteaded of C401and C405
C405 10uF/16V
C406 1000pF
C407 0.1uF
C408 4.7uF
C409 22uF(DNI)
R417 1.13K
R416 4.22K
R461 499
R418 137
C439 560pF
U402
BCM6302
QFN20+EP
AVDD
AVDD
AVDD
AVDD
AVDD_V25
INA1_P
INA2_P
IP
IN
INA2_N
INA1_N
VON
VOP
ADSL/VDSL
CTRL1
CTRL2
CTRL3
CTRL4
GND
NC = 3,13
PRELIMINARY
High current lines.
Use thicker traces.
LD1_OUT_P
LD1_OUT_N
R411 2.7
R412 11
C446 470pF
R407 2.7
High current - must use 1206 size for R407,411.
D403 WS05DLC-B(DNI)
D404 WS05DLC-B(DNI)
D405 SMAJ5.0CA(DNI)
D401 MMBD7000LT1G
D402 MMBD7000LT1G
VDSL_TX_TIP
VDSL_TX_RING
VDSL_RX_RING
VDSL_RX_TIP
T401
TRTEP13S-U636B017
RB3 0(DNI)
C436 0.033uF/400V
R476 0(DNI)
L406 4.7mH@100kHz(DNI)
L407 4.7mH@100kHz
R477 0(DNI)
S402
S401
GDT
GDT(DNI)
J401
NC2
L2TIP
L1TIP
L1RING
L2RING
NC1
RJ11-4
LINE1_TIP
LINE1_RING
R415 294
R405 294
C429 330pF
C460 8200pF
R408 88.7
C435 0.022uF
C434 0.022uF
AFE_TXP
AFE_TXN
LD1_CTRL_0
R431 10K
R432 10K
R433 10K
R434 10K
LD1_A/VDSL
LD1_CTRL1
LD1_CTRL2
LD1_CTRL3
LD1_CTRL4
R460 499
R423 137
C426 560pF
R406 4.22K
R404 1.13K
HYBRID
R468 0
C475 22pF
R466 324
C473 5600pF
R419 698
C463 0.047uF
R420 121
C450 0.1uF(DNI)
R426 432 (DNI)
R428 432 (DNI)
C452 0.1uF(DNI)
C464 0.047uF
R421 121
R422 698
R467 324
C474 5600pF
R469 0
C476 22pF
D406 WS05DLC-B(DNI)
D407 SMAJ5.0CA(DNI)
D408 WS05DLC-B(DNI)
RX Filter
C455 0.01uF
C441 0.01uF
L404 0
C444 0.1uF(DNI)
R453 0(DNI)
L401 68uH
C451 0
C453 0
L402 68uH
C454 0.01uF
C443 0.01uF
L405 0
Optional for Stopband Zero
AFE_RXP
AFE_INDSWP
AFE_INDSWN
AFE_RXN
AFE_INDSWP
VDSL_RX_RING
VDSL_RX_TIP

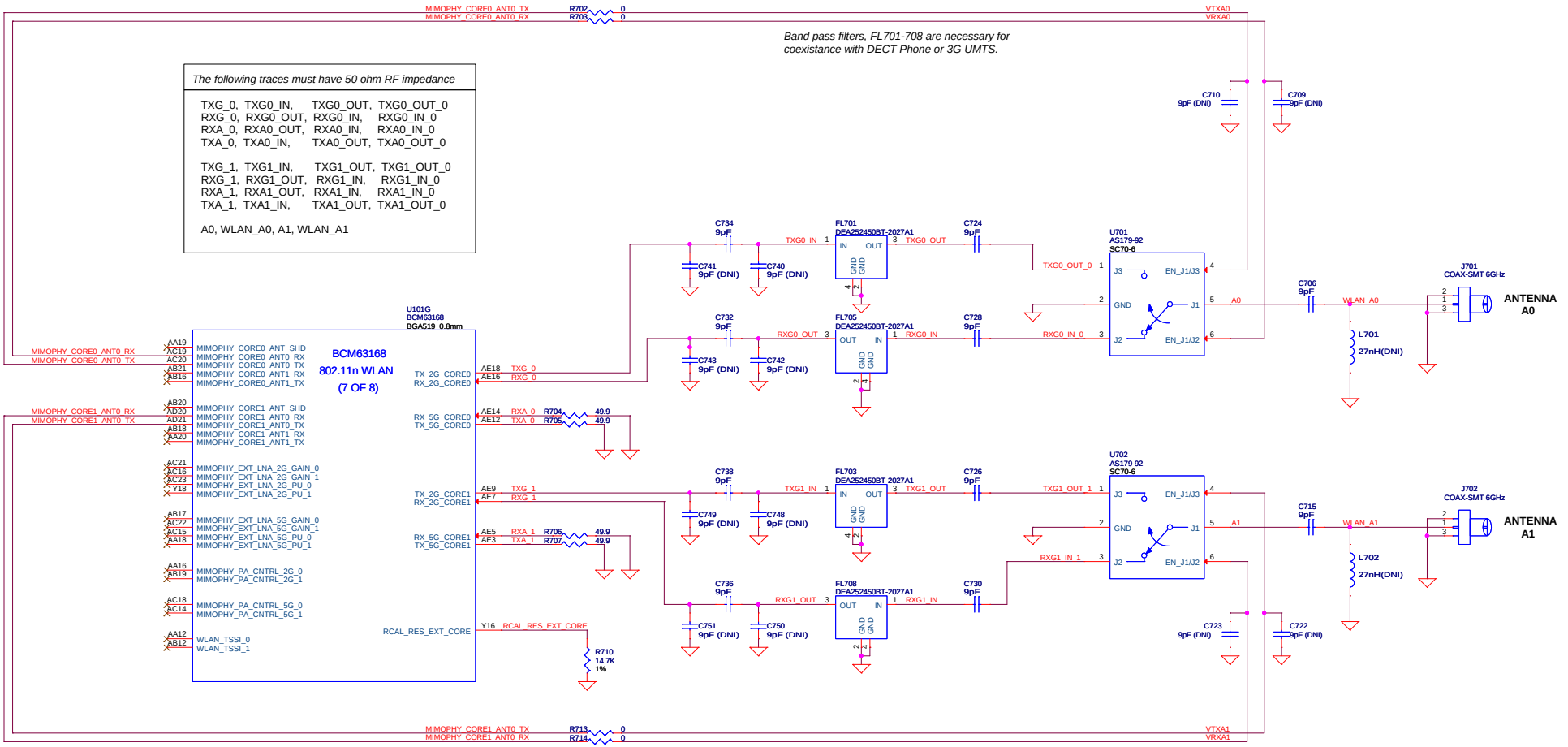
CONNECT MIIx_VDDO_1 & _2 TO 3.3V WHEN USED IN MII, RvMII, TMII MODE, OR WHEN NOT USED
CONNECT MIIx_VDDO_1 & _2 TO 2.5V WHEN USED IN RGMII MODE, OR WHEN NOT USED

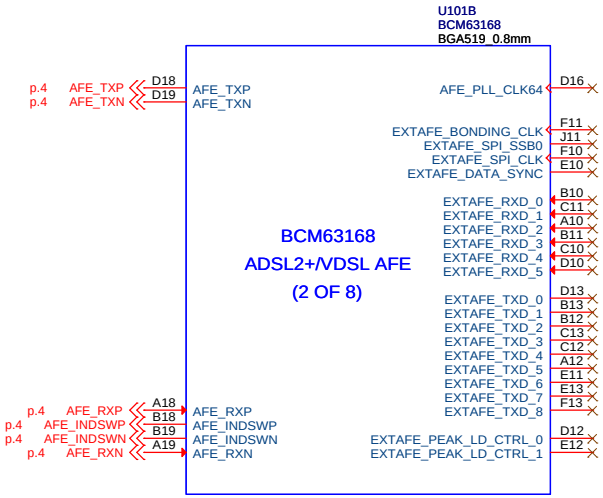
!

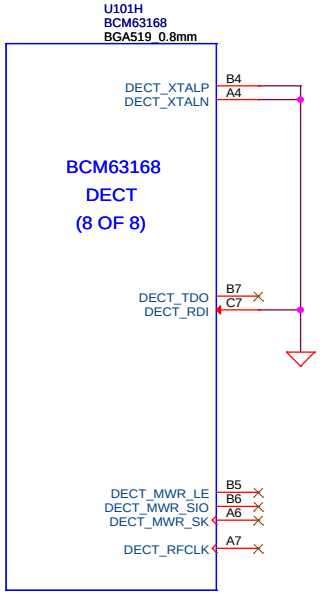
MII2_VDDO_1 & _2 PROVIDE THE I/O VOLTAGE FOR GPIO[51:40]. THEREFORE,
MII2_VDDO_1 & _2 MUST BE CONNECTED TO 3.3V WHEN ANY OF GPIO[51:40] ARE USED.




U101E
BCM63168
BGA519_0.8mm
BCM63168
POWER
(5 OF 8)
Isolate ball R15 and connect only to 1P2SWREG1_VFB for accurate voltage sense.
NOTE: Ground flooding only under the WLAN section, no ground thieving
Components inside dashed outline must be placed exactly as per BCM96362ADVNGR2 layout.
Keep voltage drop across ferrite beads to less than 1% of supply voltage.


Band pass filters, FL701-708 are necessary for coexistance with DECT Phone or 3G UMTS.
The following traces must have 50 ohm RF impedance
TXG_0, TXG0_IN, TXG0_OUT, TXG0_OUT_0
RXG_0, RXG0_OUT, RXG0_IN, RXG0_IN_0
RXA_0, RXA0_OUT, RXA0_IN, RXA0_IN_0
TXA_0, TXA0_IN, TXA0_OUT, TXA0_OUT_0
TXG_1, TXG1_IN, TXG1_OUT, TXG1_OUT_0
RXG_1, RXG1_OUT, RXG1_IN, RXG1_IN_0
RXA_1, RXA1_OUT, RXA1_IN, RXA1_IN_0
TXA_1, TXA1_IN, TXA1_OUT, TXA1_OUT_0
A0, WLAN_A0, A1, WLAN_A1
U101G
BCM63168
BGA519 0.8mm
BCM63168
802.11n WLAN
(7 OF 8)
MIMOPHY_CORE0_ANT0_TX
MIMOPHY_CORE0_ANT0_RX
MIMOPHY_CORE1_ANT0_TX
MIMOPHY_CORE1_ANT0_RX
R702 0
R703 0
R704 49.9
R705 49.9
R706 49.9
R707 49.9
R710 14.7K 1%
R713 0
R714 0
VTXA0
VRXA0
VTXA1
VRXA1
FL701 DEA252450BT-2027A1
FL705 DEA252450BT-2027A1
FL703 DEA252450BT-2027A1
FL708 DEA252450BT-2027A1
U701 AS179-92 SC70-6
U702 AS179-92 SC70-6
J701 COAX-SMT 6GHz
J702 COAX-SMT 6GHz
ANTENNA A0
ANTENNA A1
L701 27nH(DNI)
L702 27nH(DNI)
C709 9pF (DNI)
C710 9pF (DNI)
C722 9pF (DNI)
C723 9pF (DNI)
C706 9pF
C715 9pF
C724 9pF
C726 9pF
C728 9pF
C730 9pF
C734 9pF
C738 9pF
C732 9pF
C736 9pF
C740 9pF (DNI)
C741 9pF (DNI)
C742 9pF (DNI)
C743 9pF (DNI)
C748 9pF (DNI)
C749 9pF (DNI)
C750 9pF (DNI)
C751 9pF (DNI)
Y16 RCAL_RES_EXT_CORE
Wi-Fi Protected Setup Push-Button
WPS_IRQ
R708 0
R701 4.7K
C701 1000pF
C702 1000pF(DNI)
SW701 PB-SPST-MOM-R/A/9mm
WI-FI
RF_DIS_FILT_I
R709 0
R711 4.7K
C703 1000pF
C704 1000pF(DNI)
SW702 PB-SPST-MOM-R/A/9mm
+3.3V


U101B
BCM63168
BGA519_0.8mm
BCM63168
ADSL2+/VDSL AFE
(2 OF 8)
p.4 AFE_TXP
p.4 AFE_TXN
D18
D19
AFE_TXP
AFE_TXN
AFE_PLL_CLK64
D16
EXTAFE_BONDING_CLK
EXTAFE_SPI_SSB0
EXTAFE_SPI_CLK
EXTAFE_DATA_SYNC
F11
J11
F10
E10
EXTAFE_RXD_0
EXTAFE_RXD_1
EXTAFE_RXD_2
EXTAFE_RXD_3
EXTAFE_RXD_4
EXTAFE_RXD_5
B10
C11
A10
B11
C10
D10
EXTAFE_TXD_0
EXTAFE_TXD_1
EXTAFE_TXD_2
EXTAFE_TXD_3
EXTAFE_TXD_4
EXTAFE_TXD_5
EXTAFE_TXD_6
EXTAFE_TXD_7
EXTAFE_TXD_8
D13
B13
B12
C13
C12
A12
E11
E13
F13
p.4 AFE_RXP
p.4 AFE_INDSWP
p.4 AFE_INDSWN
p.4 AFE_RXN
A18
B18
B19
A19
AFE_RXP
AFE_INDSWP
AFE_INDSWN
AFE_RXN
EXTAFE_PEAK_LD_CTRL_0
EXTAFE_PEAK_LD_CTRL_1
D12
E12


U101H
BCM63168
BGA519_0.8mm
BCM63168
DECT
(8 OF 8)
DECT_XTALP
DECT_XTALN
B4
A4
DECT_TDO
DECT_RDI
B7
C7
DECT_MWR_LE
DECT_MWR_SIO
DECT_MWR_SK
DECT_RFCLK
B5
B6
A6
A7